

40mΩ, 650V, Super Junction N-Channel Power MOSFET

General Description

The Sanrise FRC65R040B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency. The FRC65R040B break down voltage is 650V and it has a high rugged avalanche characteristics. The FRC65R040B is available in TO-247 package.

Symbol

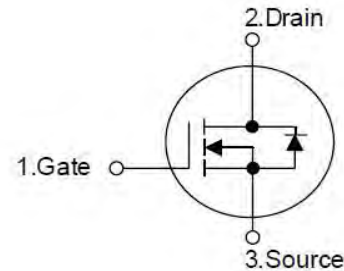


Figure 1 Symbol of FRC65R040B

Features

- Ultra Low $R_{DS(ON)} = 40m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g=210nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Non-automotive Qualified

Package Type



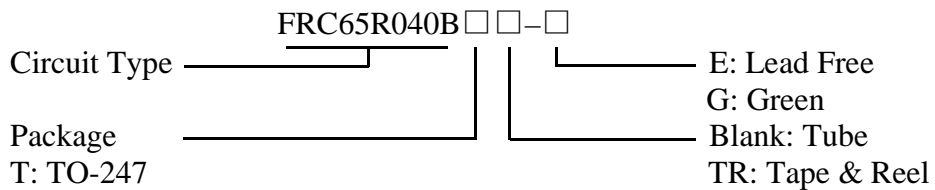
TO-247

Figure 2 Package Type of FRC65R040B

Application

- Telecom Power
- EV Charger

Ordering Information



Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
TO-247	FRC65R040BT-E	FRC65R040BT-G	SRC65R040BT	SRC65R040BTG	Tube

**40mΩ, 650V, Super Junction N-Channel Power MOSFET****Absolute Maximum Ratings**^{Note 1}

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DSS}	650	V
Gate-Source Voltage (static)	V _{GSS}	±20	V
Gate-Source Voltage (dynamic), AC (f>1 Hz)	V _{GSS}	±30	V
Continuous Drain Current	I _D	T _C =25°C	77
		T _C =125°C	34
Pulsed Drain Current (Note 2)	I _{DM}	231	A
Avalanche Energy, Single Pulse (Note 3)	E _{AS}	264	mJ
Avalanche Energy, Repetitive (Note 2)	E _{AR}	0.264	mJ
Avalanche Current, Repetitive (Note 2)	I _{AR}	2.8	A
Continuous Diode Forward Current	I _S	77	A
Diode Pulse Current	I _{S,PULSE}	231	A
MOSFET dv/dt Ruggedness, V _{DS} ≤480V	dv/dt	80	V/ns
Reverse Diode dv/dt, V _{DS} ≤480V, I _{SD} ≤I _D	dv/dt	50	V/ns
Operating Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)	T _{LEAD}	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. I_{AS}=2.8A, V_{DD} = 60V, R_G = 25Ω, Starting T_J = 25°C

Thermal characteristics

Parameter (TO247-package)	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	-		0.22	°C/W
Thermal Resistance, Junction-to-Ambient	R _{thJA}	-		62	

**40mΩ, 650V, Super Junction N-Channel Power MOSFET****Electrical Characteristics**T_J = 25°C, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	650			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V			20	uA
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} =20V, V _{DS} =0V		100	nA
	Reverse	I _{GSSR}	V _{GS} =-20V, V _{DS} =0V		-100	
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =1.85mA	3.5	4.3	5.0	V
Static Drain-Source On-Resistance	R _{Ds(ON)}	V _{GS} =10V, I _D =34A		35	40	mΩ
Gate Resistance	R _G	f=1MHz, Open Drain		2.0		Ω
Dynamic Characteristics						
Input Capacitance	C _{ISS}	V _{DS} =25V, V _{GS} =0V, f=1MHz		4.9		nF
Output Capacitance	C _{OSS}			4.8		nF
Reverse Transfer Capacitance	C _{RSS}			341		pF
Effective output capacitance, energy related ^{NOTE5}	C _{O(er)}	V _{GS} =0V, V _{DS} =0...480V		185		pF
Effective output capacitance, time related ^{NOTE6}	C _{O(tr)}			1264		
Turn-on Delay Time	t _{d(on)}	V _{DD} =400V, I _D =34A R _G =3.3Ω, V _{GS} =10V		14		ns
Rise Time	t _r			8		
Turn-off Delay Time	t _{d(off)}			102		
Fall Time	t _f			6.1		
Gate Charge Characteristics						
Gate to Source Charge	Q _{gs}	V _{DD} =480V, I _D =34A V _{GS} =0 to 10V		31.7		nC
Gate to Drain Charge	Q _{gd}			104		
Gate Charge Total	Q _g			210		
Gate Plateau Voltage	V _{plateau}			6.3		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _{SD} =34A		0.86	1.1	V
Reverse Recovery Time	t _{rr}	V _R =400V, I _F =34A dI _F /dt=100A/us		176		ns
Reverse Recovery Charge	Q _{rr}			1.28		uC
Peak Reverse Recovery Current	I _{rrm}			14.5		A

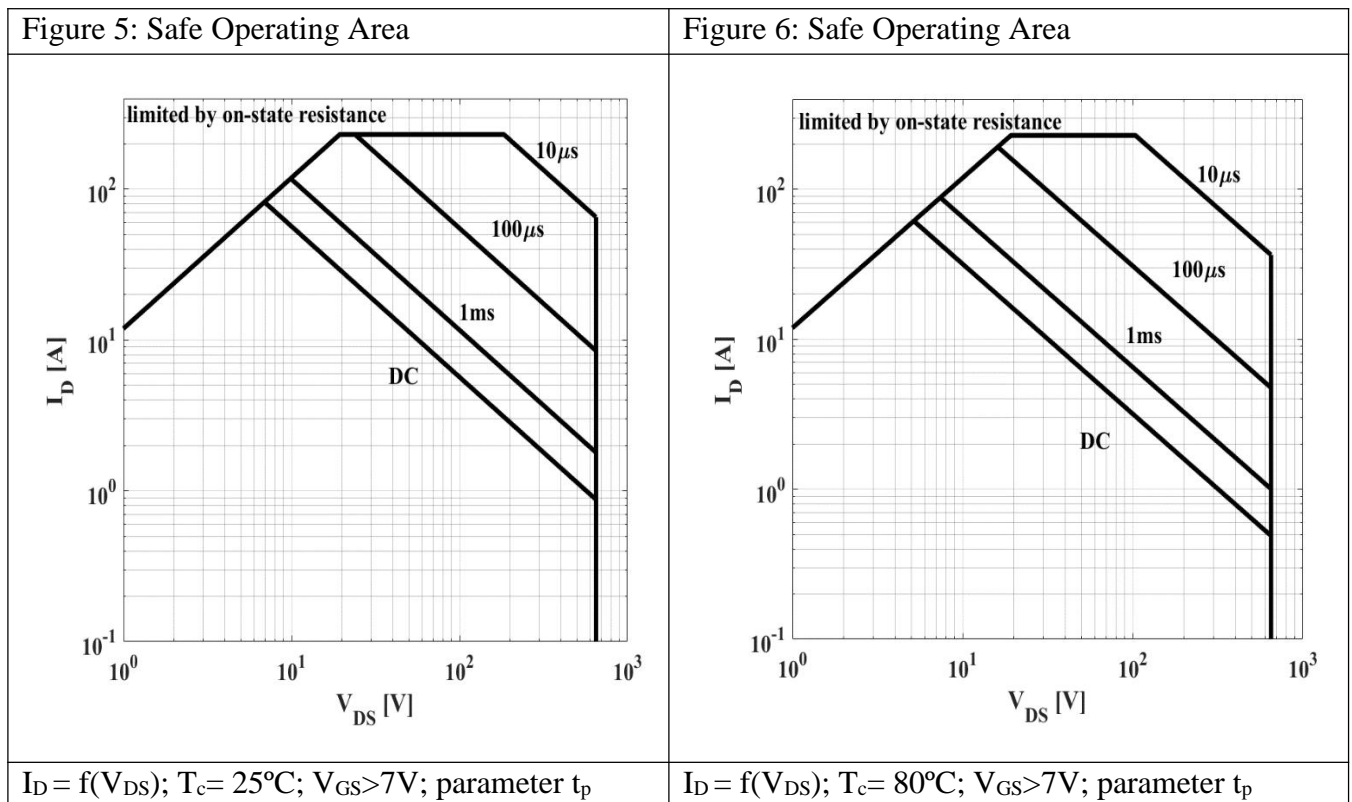
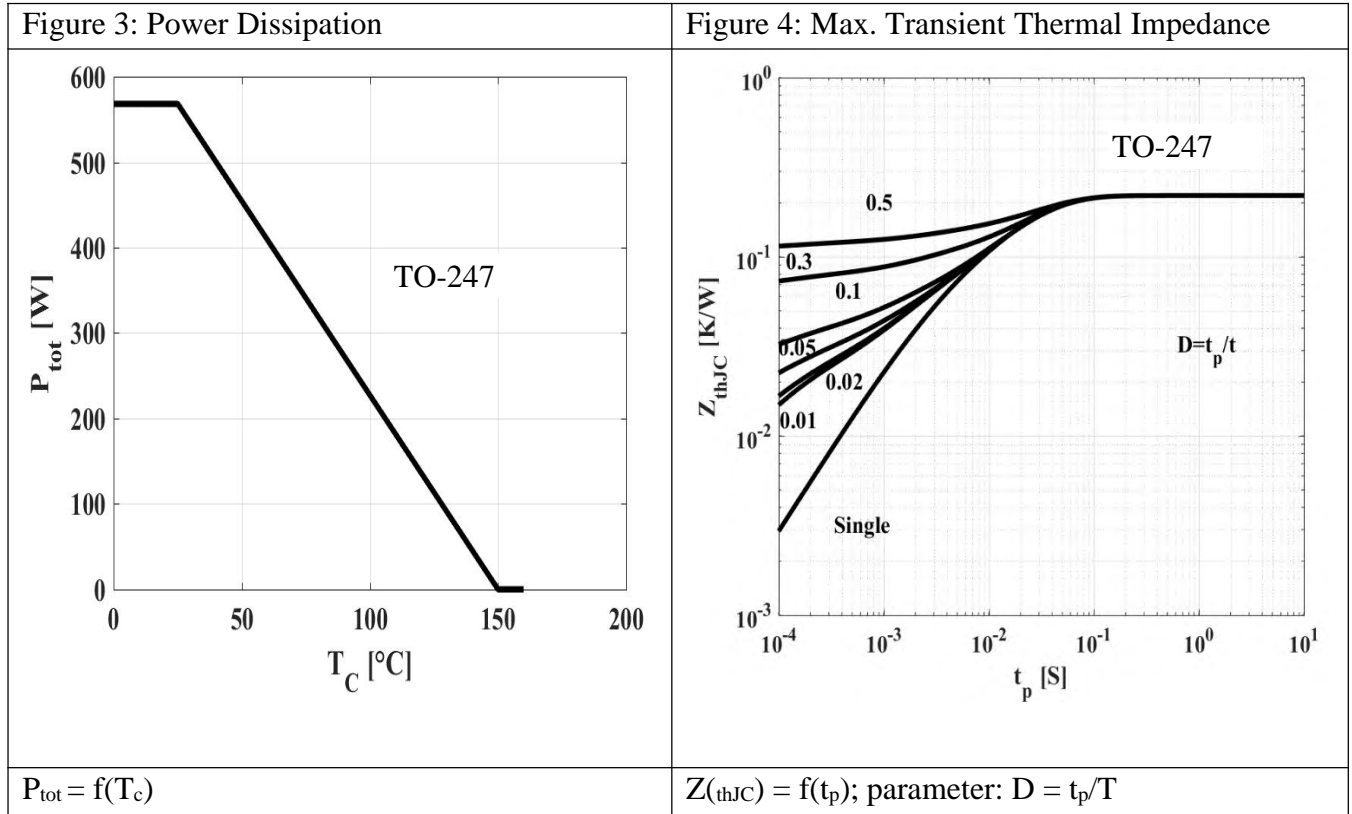
Note:

- C_{O(er)} is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V
- C_{O(tr)} is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480 V



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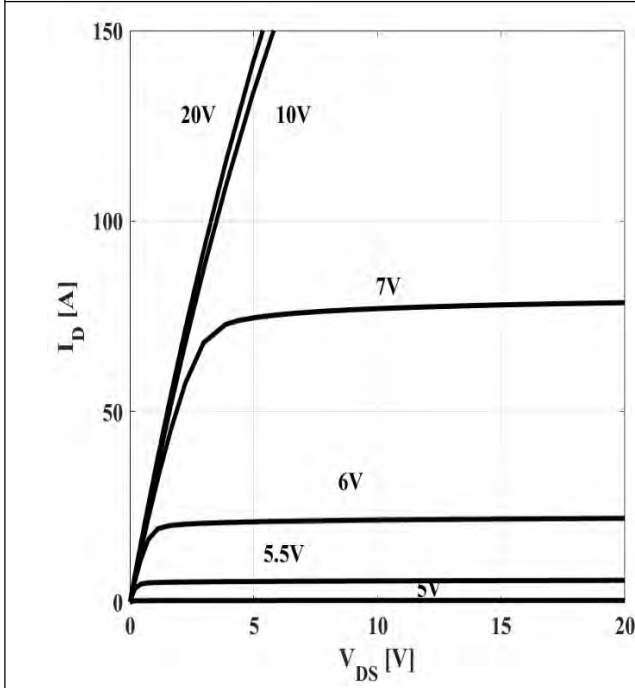
Typical Performance Characteristics





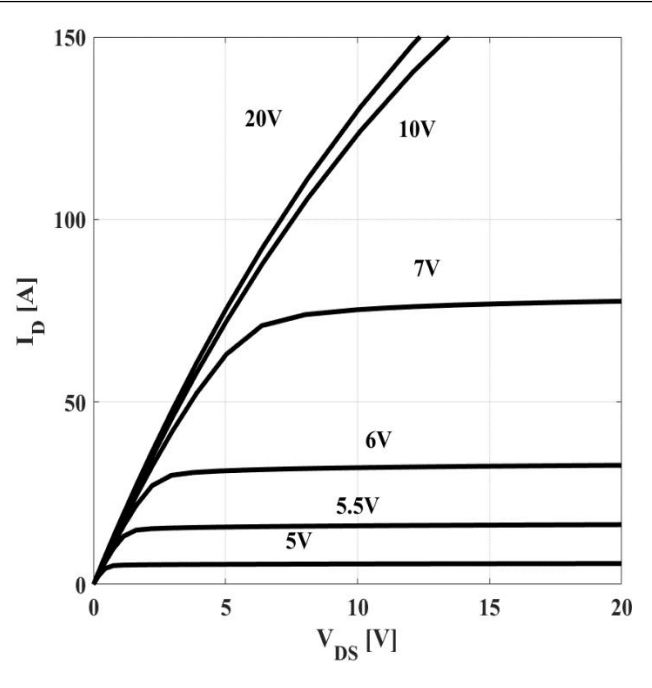
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Figure 7: Typ. Output Characteristics



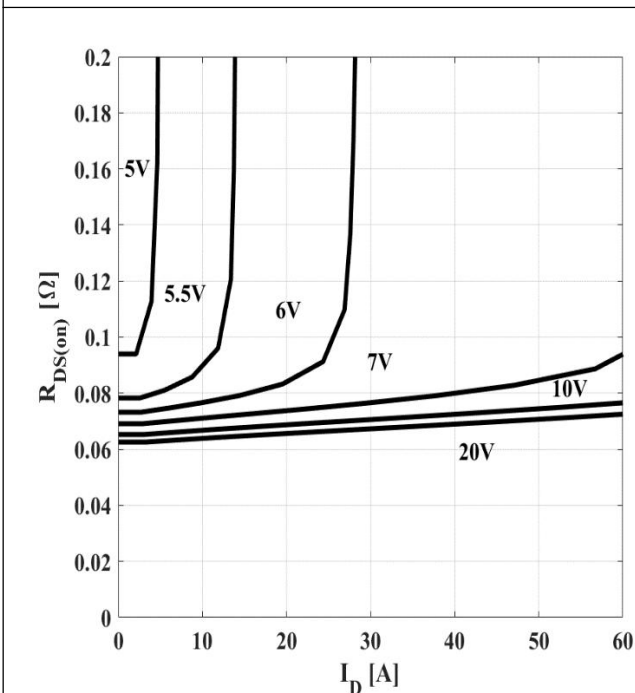
$I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$

Figure 8: Typ. Output Characteristics



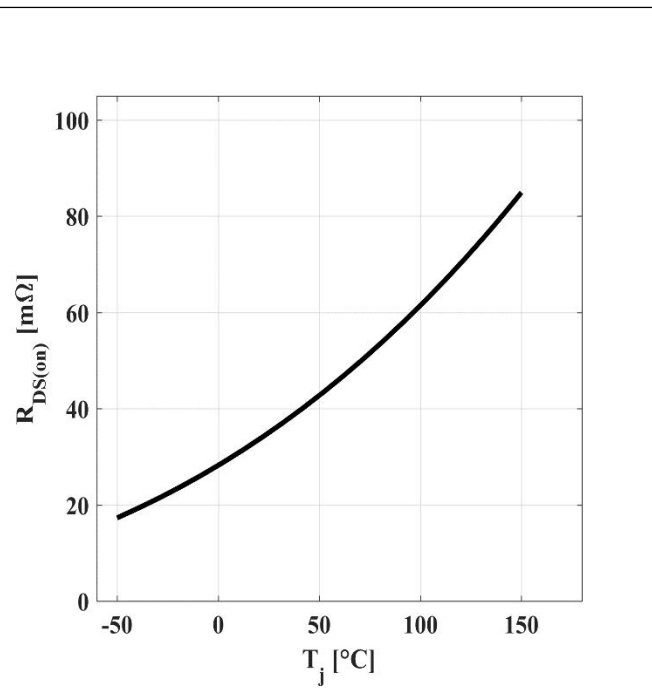
$I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$

Figure 9: Typ. Drain-Source On-State Resistance



$R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$

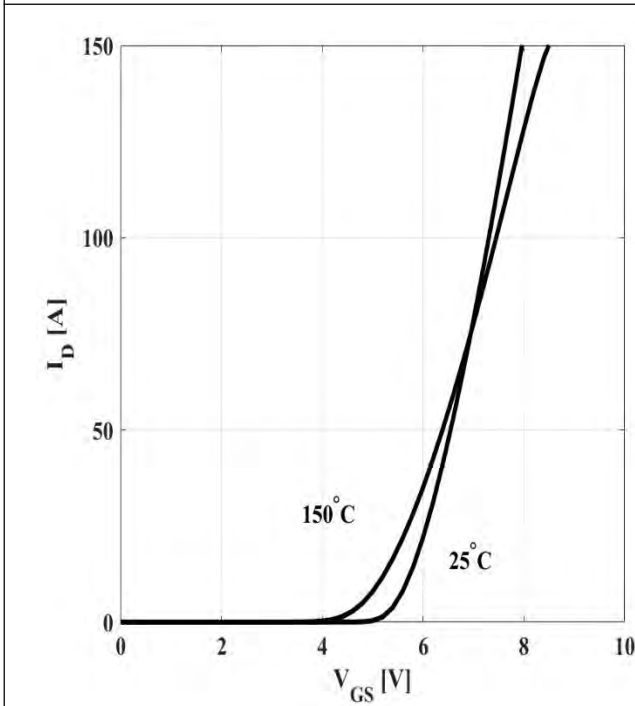
Figure 10: Typ. Drain-Source On-State Resistance



$R_{DS(ON)} = f(T_j); I_D = 34\text{A}; V_{GS} = 10\text{V}$

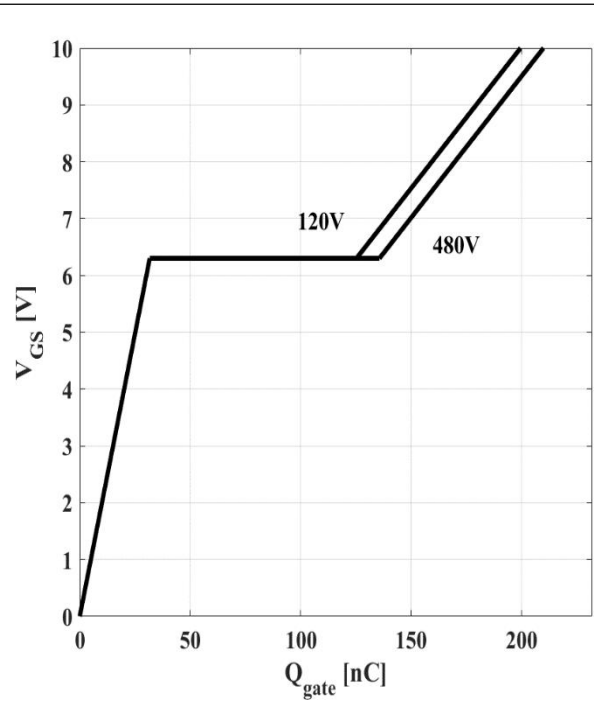
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Figure 11: Typ. Transfer Characteristics



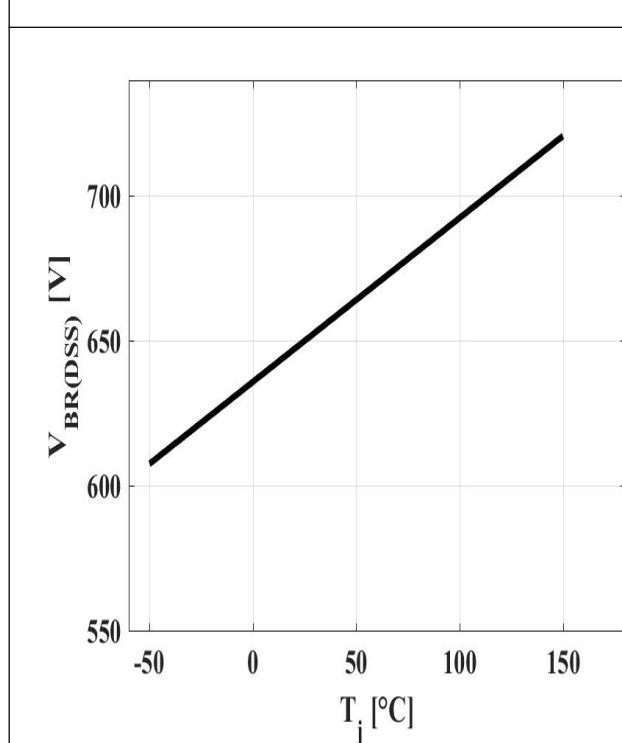
$I_D = f(V_{GS}); V_{DS} = 20V$

Figure 12: Typ. Gate Charge



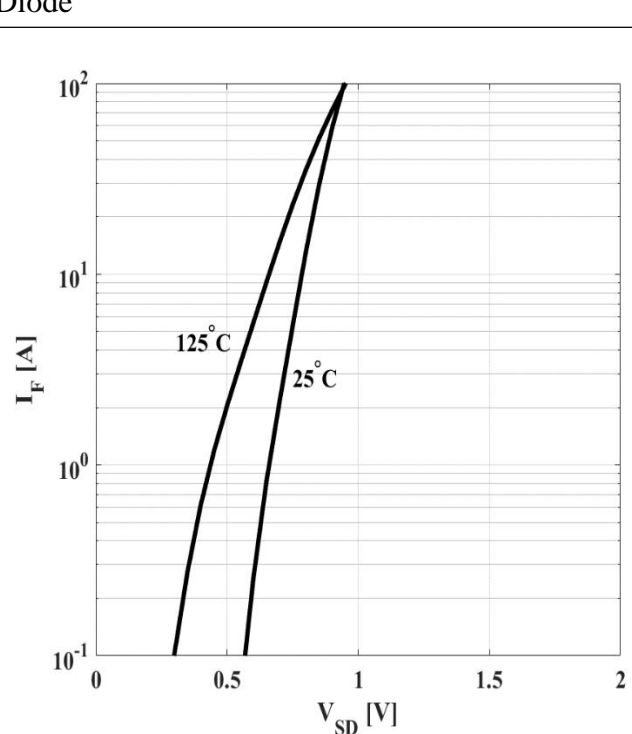
$V_{GS} = f(Q_{gate}), I_D = 34A \text{ pulsed}$

Figure 13: Drain-Source Breakdown Voltage



$V_{BR(DSS)} = f(T_j); I_D = 10mA$

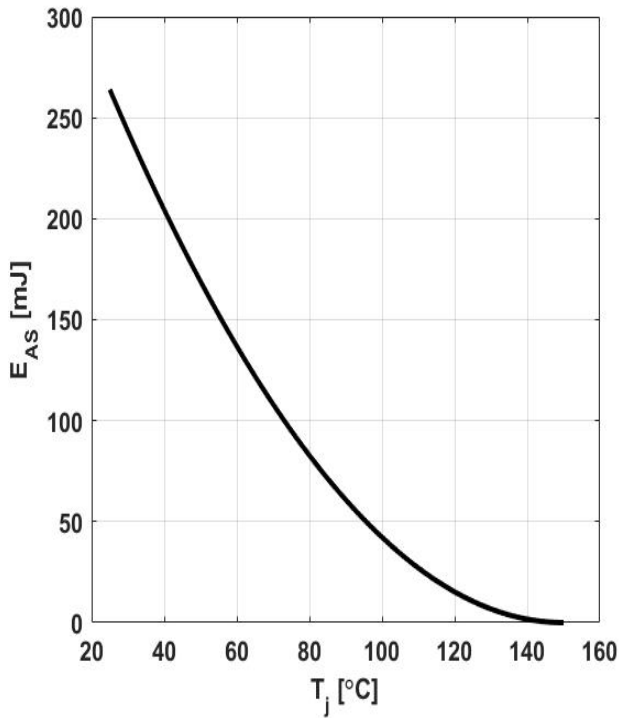
Figure 14: Forward Characteristics of Reverse Diode



$I_F = f(V_{SD}); \text{parameter: } T_j$

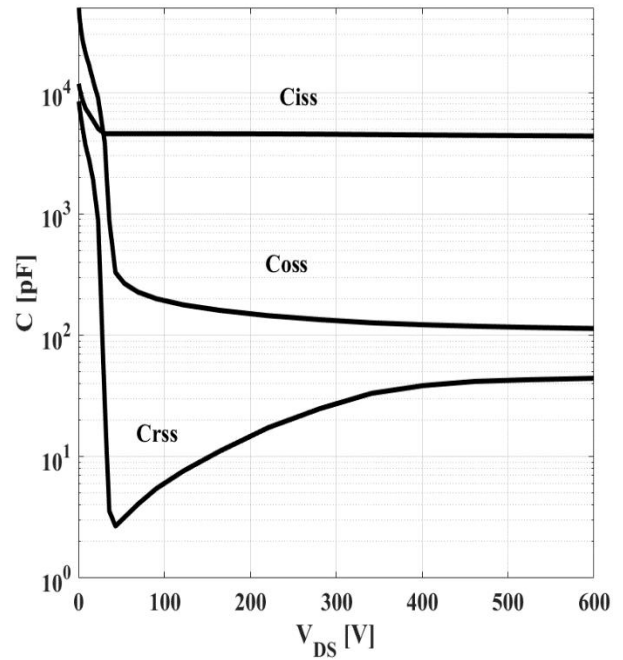
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Figure 15: Avalanche Energy



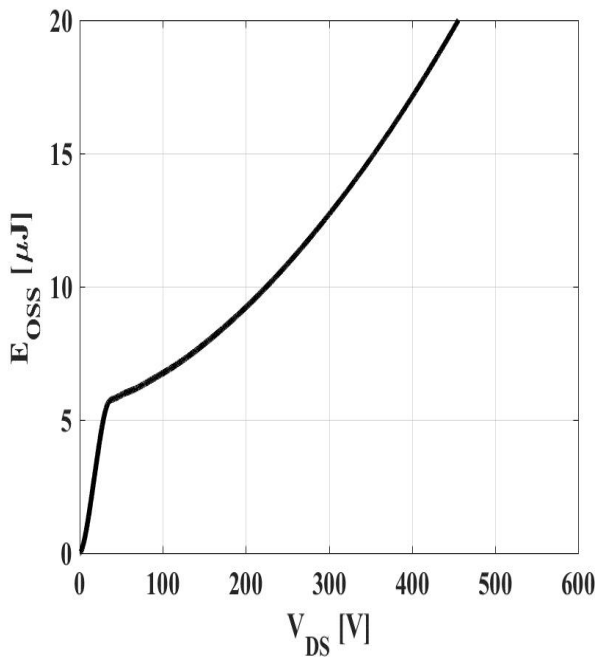
$E_{AS}=f(T_j)$; $I_D=2.8A$; $V_{DD}=60V$

Figure 16: Typ. Capacitances



$C=f(V_{DS})$; $V_{GS}=0$; $f=1MHz$

Figure 17: Coss Stored Energy

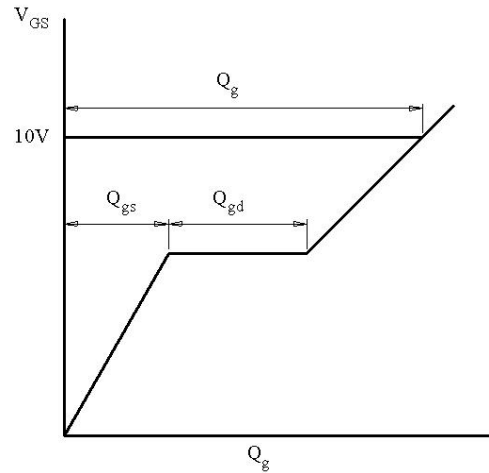
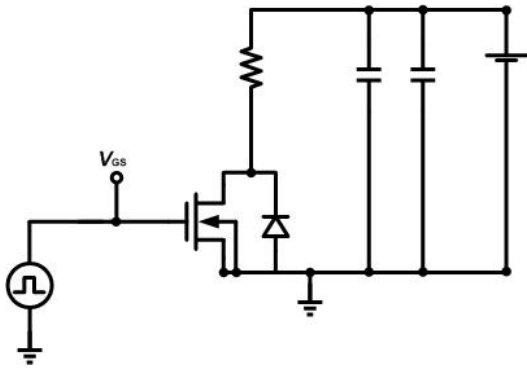


$E_{OSS}=f(V_{DS})$

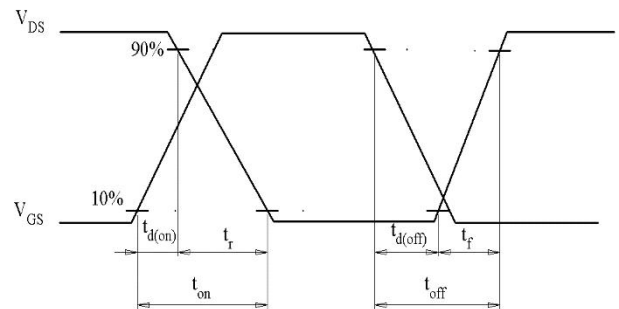
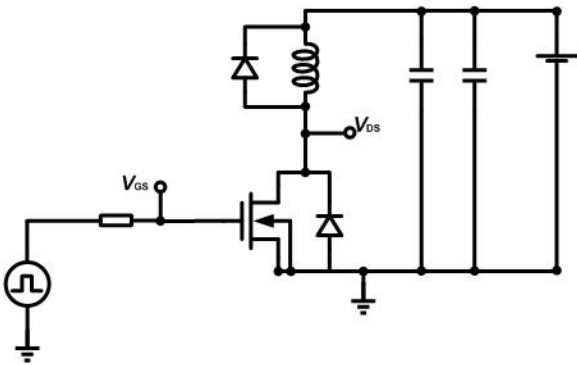
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Test Circuits

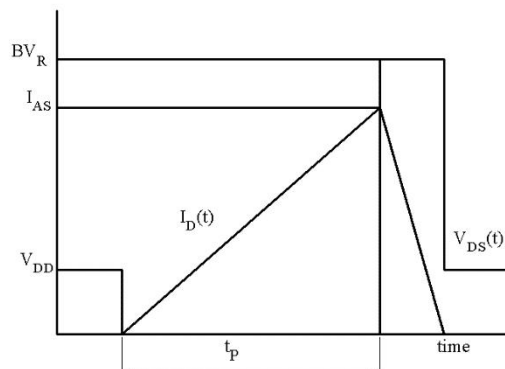
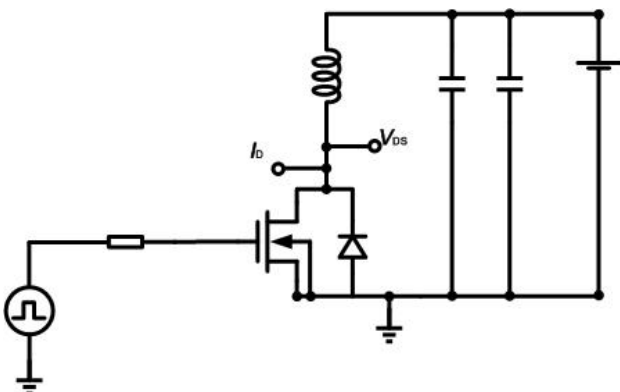
1. Gate Charge Test Circuit & Waveform



2. Switch Time Test Circuit

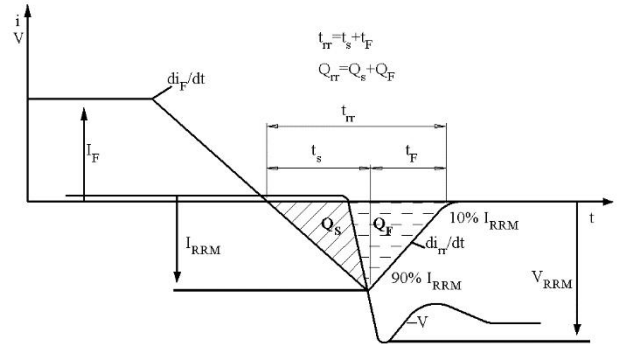
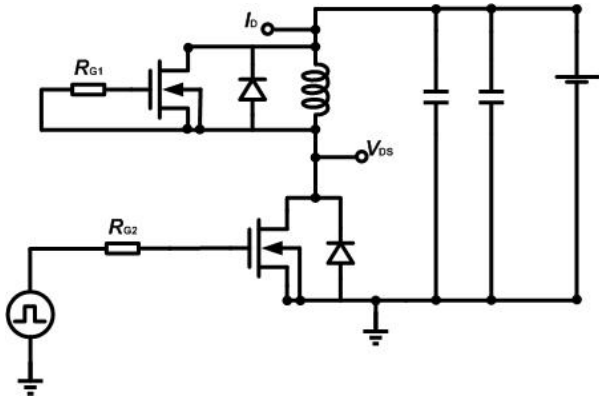


3. Unclamped Inductive Switching Test Circuit & Waveforms



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4. Test Circuit and Waveform for Diode Characteristics

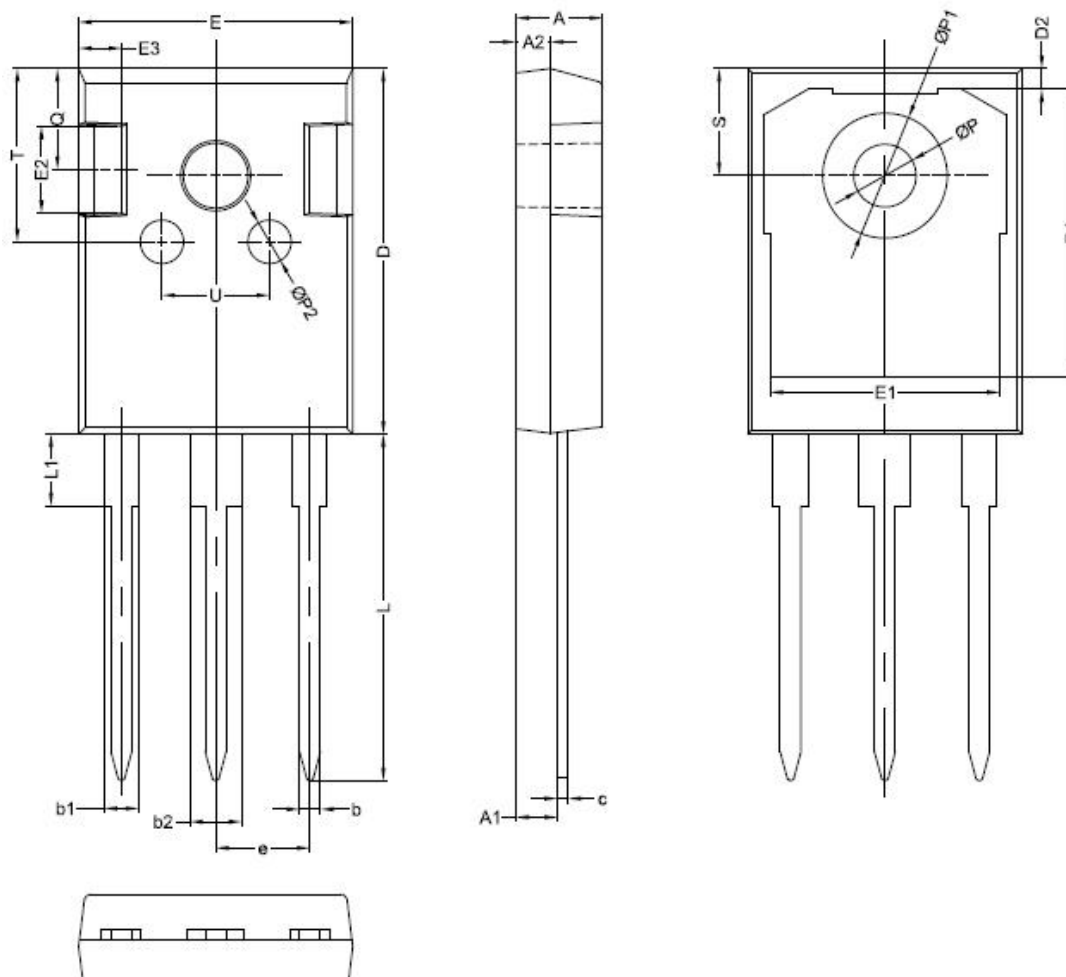


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Mechanical Dimensions

TO-247

Unit: mm



Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E2	-	5.00	-
A1	2.21	2.41	2.61	E3	-	2.50	-
A2	1.90	2.00	2.10	e	5.44(BSC)		
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	-	7.40
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.00	T	-	10.00	-
E1	-	13.30	-	U	-	6.20	-